



Material Content Data Sheet



Sales Product Name				BSZ036NE2LS		Issued		29. August 2013	
MA#				MA001042926					
Package				PG-TSDSON-8-25		Weight*		35.42 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.285	0.80	0.80	8033	8033	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		69		
	non noble metal	zinc	7440-66-6	0.010	0.03		278		
	non noble metal	iron	7439-89-6	0.197	0.56		5555		
wire	non noble metal	copper	7440-50-8	7.988	22.55	23.15	225549	231451	
	noble metal	gold	7440-57-5	0.029	0.08	0.08	830	830	
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.11		1077	
encapsulation	plastics	epoxy resin	-	1.965	5.55		55473		
	inorganic material	silicondioxide	60676-86-0	17.072	48.19	53.85	482025	538575	
leadfinish	non noble metal	tin	7440-31-5	0.395	1.12	1.12	11160	11160	
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	574	574	
solder	noble metal	silver	7440-22-4	0.012	0.03		327		
	non noble metal	tin	7440-31-5	0.009	0.03		262		
	non noble metal	lead	7439-92-1	0.442	1.25	1.31	12490	13079	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33		
	non noble metal	zinc	7440-66-6	0.005	0.01		133		
	non noble metal	iron	7439-89-6	0.094	0.27		2653		
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.77	11.05	107741	110560	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		26		
	non noble metal	zinc	7440-66-6	0.004	0.01		103		
heat sink CLIP	non noble metal	iron	7439-89-6	0.073	0.21		2058		
	non noble metal	copper	7440-50-8	2.959	8.36	8.58	83551	85738	
*deviation	< 10%		Sum in total:			100.00		1000000	

Important Remarks:

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